

Shutesh Krishnan

List of Publications by Year in descending order

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Version: 2024-02-01

17
papers

207
citations

1163117

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1372567

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18
all docs

18
docs citations

18
times ranked

368
citing authors

#	ARTICLE	IF	CITATIONS
1	Incorporation of iron oxide into CNT/GNF as a high-performance supercapacitor electrode. <i>Materials Chemistry and Physics</i> , 2018, 212, 318-324.	4.0	12
2	Incorporation of Zinc Oxide into Carbon nanotube/Graphite nanofiber as high performance supercapacitor electrode. <i>Electrochimica Acta</i> , 2017, 228, 259-267.	5.2	39
3	Physicochemical and electrochemical properties of carbon nanotube/graphite nanofiber hybrid nanocomposites for supercapacitor. <i>Journal of Power Sources</i> , 2016, 328, 195-202.	7.8	33
4	Characterization of Boron-Based Nanomaterial Enhanced Additive in Water-Based Drilling Fluids: A study on Lubricity, Drag, ROP and Fluid Loss Improvement. , 2016, , .		7
5	One-pot synthesis of graphene oxide sheets and graphene oxide quantum dots from graphite nanofibers. <i>Journal of Nanoparticle Research</i> , 2015, 17, 1.	1.9	9
6	One dimensional CuO nanocrystals synthesis by electrical explosion: A study on structural, optical and electronic properties. <i>Journal of Alloys and Compounds</i> , 2014, 586, 360-367.	5.5	24
7	Low dimensional CuO nanocomposites synthesis by pulsed wire explosion and their crystal growth mechanism. <i>Ceramics International</i> , 2014, 40, 9907-9916.	4.8	10
8	Synthesis and growth kinetics of spindly CuO nanocrystals via pulsed wire explosion in liquid medium. <i>Journal of Nanoparticle Research</i> , 2013, 15, 1.	1.9	24
9	Advanced materials for drop in solution to Pb in high temp solders: The next generation of zinc based solder alloy. , 2013, , .		1
10	Preparation and Low-Temperature Sintering of Cu Nanoparticles for High-Power Devices. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , 2012, 2, 587-592.	2.5	38
11	Synthesis of CuO nanocomposites with various morphologies via pulsed wire explosion. , 2012, , .		1
12	Fabrication of one-dimensional CuO nanocrystals via pulsed wire explosion: structural, optical and electronic characterizations. , 2012, , .		0
13	Lead-free solder paste selection and solder joint reliability for copper stud flip chip. , 2008, , .		3
14	Effect of Product Design and Materials on Large Leadless Package Reliability. <i>Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International</i> , 2007, , .	0.0	1
15	Treated Lead-frame for Leaded Plastic Molded Package. <i>Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International</i> , 2007, , .	0.0	0
16	Influence of Material Combination on Package Stress and Verification of Numerical Model. , 2006, , .		2
17	Leadframe Material, Design and Surface Treatment for MSL 1 260Â°C Package Robustness. <i>Electronics Manufacturing Technology Symposium (IEMT), IEEE/CPMT International</i> , 2006, , .	0.0	3